



40GBASE-SR4 850nm MMF 300m QSFP+ Optical Transceiver with Duplex MPO Connector

40GMSRSFPC



DESCRIPTION

The 40GMSRSFPC QSFP+ 40GBASE-SR4 Transceiver product is a new high-speed module with a MPO connector. This interconnecting module offers 4 channels and maximum bandwidth of 40Gbps. The TRxs utilize multimode fiber with 850-nm VCSELs and PIN PDs. This module provides high performance and excellent efficiency in the optical communication.

FEATURES

- Compliant with 40G Ethernet IEEE 802.3ba 40GBASE-SR4 standards
- QSFP footprint (Quad small form-factor, pluggable)
- Low power dissipation < 1.5W
- Full Digital Diagnostics Monitor Interface
- 0 to 70°C case temperature operating range
- Hot pluggable electrical interface
- RoHS-6 Compliant
- Up to 100m over OM3 fiber
- Up to 150m over OM4 fiber

APPLICATIONS

- 40GBASE-SR4 Ethernet links
- Infiniband QDR, DDR & SDR interconnects
- Client-side 40G Telecom connections
- 4G/8G/10G Fiber Channel
- SATA/SAS Storage

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	MIN	MAX	UNIT
Storage Temperature	T _s	-40	85	°C
Supply Voltage	V _{CC}	-0.5	3.6	V
Data Input Voltage – Single Ended		-0.5	V _{CC} +0.5	V
Relative Humidity	RH	5	85	%
Rx Optical Damage Threshold / Lane	DT	3.4		dBm

RECOMMENDED OPERATING CONDITIONS

PARAMETER	SYMBOL	MIN	TYP.	MAX	UNIT
Case Operating Temperature	T _c	0	40	70	°C
3.3V Power Supply Voltage	V _{CC}	3.135	3.3	3.465	V
Signal Rate per Channel	B	10.3125			Gb/s
Control Input Voltage High	V _{Ih}	2		V _{CC} +0.3	V
Control Input Voltage Low	V _{Il}	-0.3		0.8	V
Two Wire Serial (TWS) Interface Clock Rate				400	KHz
Receiver Differential Data Output Load	Z _d		100		Ohms
Fiber Length: 500MHz z•km 50µm MMF (OM2)		0.5		30	m
Fiber Length: 2000MHz z•km 50µm MMF (OM3)		0.5		100	m
Fiber Length: 4700MHz z•km 50µm MMF (OM4)		0.5		150	m

TRANSMITTER ELECTRICAL CHARACTERISTICS

PARAMETER	SYMBOL	MIN	TYP.	MAX	UNIT	NOTE
Power Consumption	P			1.5	W	
Power Supply Current	I _{CC}			420	mA	
TRx Power-On Initialization Time				2000	ms	Note 1
Data Input Differential Peak-to-Peak Voltage Swing	V _{DIFF}	200		1200	mV _{pp}	
Differential Input Return Loss	Per IEEE 802.3ba, Section 86A.4.1.1				dB	Note 2
Differential to Common Mode Input Return Loss		10			dB	Note 2
J2 Jitter Tolerance	Jt2	0.17			UI	
J9 Jitter Tolerance	Jt9	0.29			UI	
Eye Mask Coordinates: X1, X2; Y1, Y2		Specification Value 0.11, 0.31; 95, 350			UI; mV	Note 3

RECEIVER ELECTRICAL CHARACTERISTICS

PARAMETER	SYMBOL	MIN	TYP.	MAX	UNIT	NOTES
Data Output Differential Peak-to-Peak Voltage Swing		200		900	mVpp	Note 4
Output Transition Time 20% to 80%	Tr, Tf	28			ps	
Differential Output Return Loss	Per IEEE 802.3ba, Section 86A.4.2.1				dB	Note 2
Common Mode Output Return Loss	Per IEEE 802.3ba, Section 86A.4.2.2				dB	Note 2
Output Total Jitter				62	ps	
J2 Jitter Output	Jo2			0.42	UI	
J9 Jitter Output	Jo9			0.65	UI	
Eye Mask Coordinates: X1, X2; Y1, Y2		Specification Value 0.25, 0.5; 150, 425			UI; mV	Note 3

Notes:

1. “Initialization Time” is the time from when the supply voltages reach and remain above the minimum “Recommended Operating Conditions” to the time when the module enables TWS access. The module at that point is fully functional.
2. 10M to 11.1 GHz according to IEEE 802.3ba specification.
3. Hit ratio= 5×10^{-5} per sample.
4. AC-Coupled with 100Ω differential output impedance.

TRANSMITTER OPTICAL CHARACTERISTICS

PARAMETER	SYMBOL	MIN	TYP.	MAX	UNIT	NOTE
Central Wavelength	λ	840		860	nm	
Spectral Width – RMS	$\Delta\lambda$			0.65	nm	
Average Output Power, each lane	PO	-7.6		2.4	dBm	
Output Optical Modulation Amplitude, per lane	OMA	-5.6			dBm	
Difference in Power between any Two Lanes in OMA				4.0	dB	
Transmitter and Dispersion Penalty (TDP), each lane	TDP			3.5	dB	
Optical Extinction Ratio	ER	3			dB	
Disabled Output Optical Power	PO_OFF			-30	dBm	
Eye Mask Coordinates: X1, X2, X3; Y1, Y2, Y3		0.23, 0.34, 0.43; 0.27, 0.35, 0.4			UI	Note 1

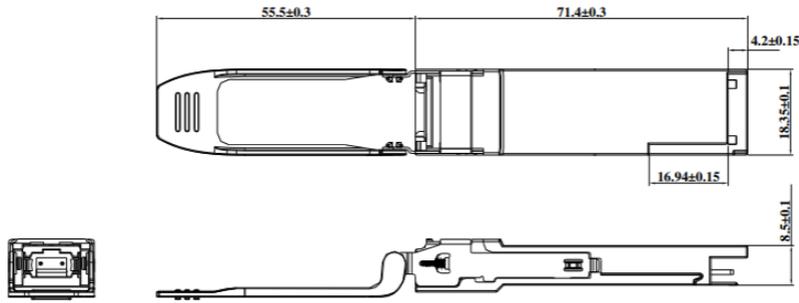
RECEIVER OPTICAL CHARACTERISTICS

PARAMETER	SYMBOL	MIN	TYP.	MAX	UNIT	NOTE
Central Wavelength, each lane	λ	840	850	860	nm	
Damage Threshold		3.4			dBm	
Average Power at Receiver Input, each lane	P _{IN}	-9.5		2.4	dBm	
Stressed Sensitivity (OMA)				-5.4	dBm	Note 2
Non-Stressed Sensitivity (Average), each lane				-7.5	dBm	Note 2
LOS Assert	P _A	-30			dBm	
LOS De-Assert	P _D			-9	dBm	
LOS Hysteresis		0.5			dB	

Notes:

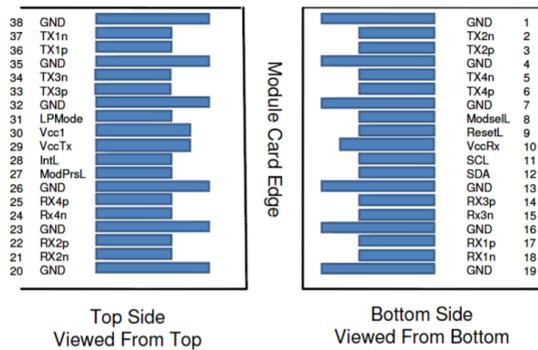
1. Hit ratio= 5×10^{-5} per sample.
2. Measured with 10.3125-Gbps of PRBS-31 at 10-12 BER.

DIMENSIONS



DIMENSIONS ARE IN MILLIMETERS

PAD ASSIGNMENT AND DESCRIPTION



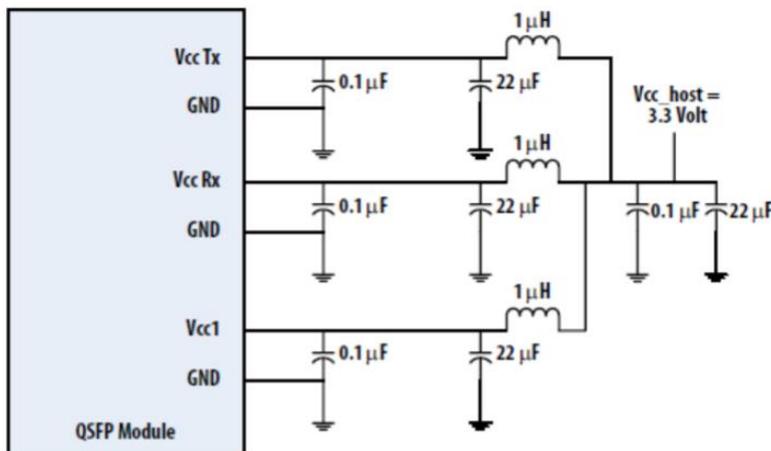
PIN	LOGIC	SYMBOL	DESCRIPTION	PLUG SEQUENCE	NOTE
1		GND	Ground	1	Note 1
2	CML-I	Tx2n	Transmitter Inverted Data Input	3	
3	CML-I	Tx2p	Transmitter Non-Inverted Data Input	3	
4		GND	Ground	1	Note 1
5	CML-I	Tx4n	Transmitter Inverted Data Input	3	
6	CML-I	Tx4p	Transmitter Non-Inverted Data Input	3	
7		GND	Ground	1	Note 1
8	LVTTL-I	ModSelL	Module Select	3	
9	LVTTL-I	ResetL	Module Reset	3	
10		Vcc Rx	+3.3V Power Supply Receiver	2	Note 2
11	LVCMOS-I/O	SCL	2-wire serial interface clock	3	
12	LVCMOS-I/O	SDA	2-wire serial interface data	3	
13		GND	Ground	1	Note 2
14	CML-O	Rx3p	Receiver Non- Inverted Data Output	3	
15	CML-O	Rx3n	Receiver Inverted Data Output	3	
16		GND	Ground	1	Note 1
17	CML-O	Rx1p	Receiver Non- Inverted Data Output	3	
18	CML-O	Rx1n	Receiver Inverted Data Output	3	
19		GND	Ground	1	Note 1
20		GND	Ground	1	Note 1
21	CML-O	Rx2n	Receiver Inverted Data Output	3	

22	CML-O	Rx2P	Receiver Non- Inverted Data Output	3	
23	Logic	GND	Ground	1	Note 1
24	CML-O	Rx4n	Receiver Inverted Data Output	3	
25	CML-O	Rx4p	Receiver Non- Inverted Data Output	3	
26		GND	Ground	1	Note 1
27	LVTTL-O	ModPrsL	Module Present	3	
28	LVTTL-O	IntL	Interrupt	3	
29	LVC MOS-I/O	Vcc Tx	+3.3V Power Supply transmitter	2	Note 2
30		Vcc1	+3.3V Power Supply	2	Note 2
31	LVTTL-I	LPMode	Low Power Mode	3	
32		GND	Ground	1	Note 1
33	CML-I	Tx3p	Transmitter Non- Inverted Data Input	3	
34	CML-I	Tx3n	Transmitter Inverted Data Input	3	
35		GND	Ground	1	Note 1
36	CML-I	Tx1p	Transmitter Non- Inverted Data Input	3	
37	CML-I	Tx1n	Transmitter Inverted Data Input	3	
38		GND	Ground	1	Note 1

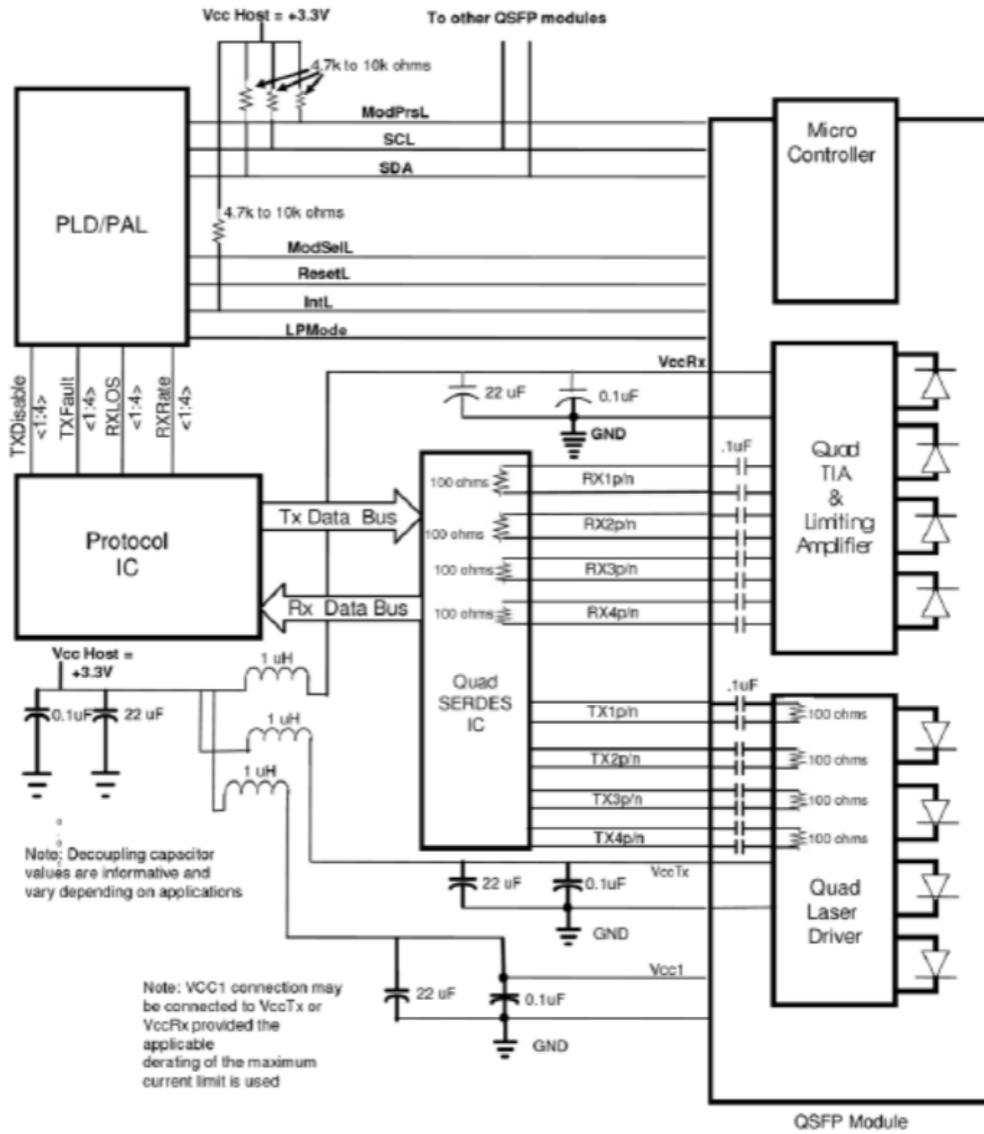
Note 1: GND is the symbol for signal and supply (power) common for the QSFP module. All are common within the QSFP+ module and all module voltages are referenced to this potential unless otherwise noted. Connect these directly to the host board signal-common ground plane.

Note 2: Vcc Rx, Vcc1 and Vcc Tx are the receiver and transmitter power supplies and shall be applied concurrently. Requirements defined for the host side of the Host Edge Card Connector are listed in Table. Recommended host board power supply filtering is shown in Host board power supply circuit. Vcc Rx Vcc1 and Vcc Tx may be internally connected within the QSFP+ module in any combination. The connector pins are each rated for a maximum current of 500 mA.

HOST BOARD POWER SUPPLY CIRCUIT

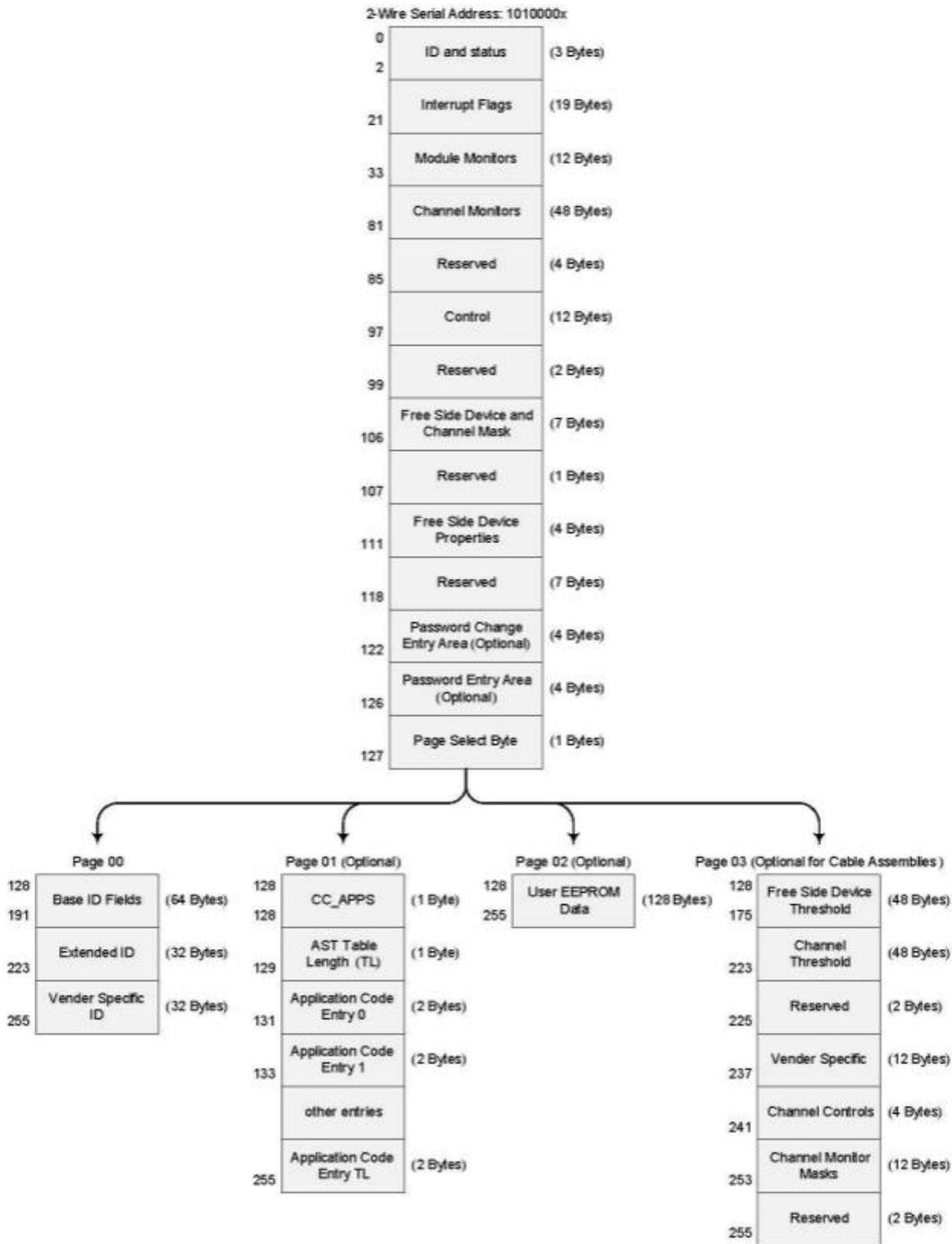


RECOMMENDED INTERFACE CIRCUIT



MEMORY MAP

The memory map is structured as a single address and multiple page approaches, according to the QSFP+ SFF-8436 MSA specification as shown in the below. For more detailed description of this memory map or lower pages, please see our Memory Map document with flexible customization settings.



ADDITIONAL NOTES

- Avoid eye or skin exposure to laser radiations.
- The device is sensitive to electro-static discharge (ESD). The device should be handled with ESD proof tools. To assemble the device on PCB, proper grounding is required to prevent ESD.
- Specifications are subject to change without notice.



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